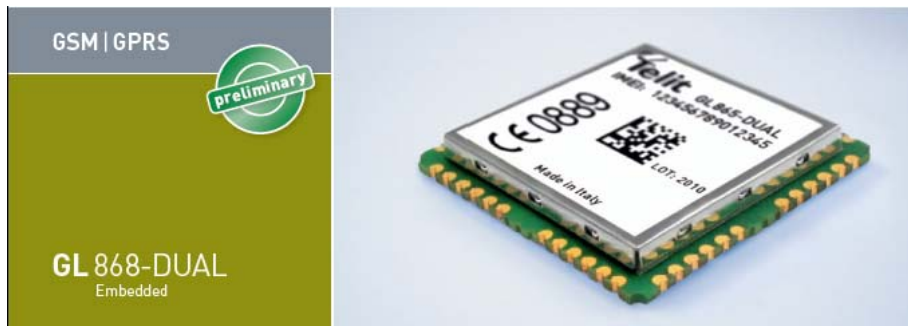
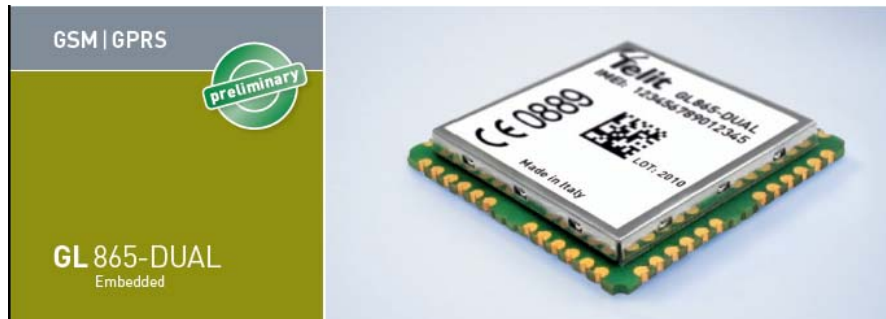


Designed for:

- Compact applications with increased autonomy
- Applications that require chip packaging



Main characteristics:

- SMT mount technology (LCC form factor)
- Dimensions: 24,4 x 24,4 x 2,7 mm
- Weight: 3,5g
- Dual-band EGSM 900 / 1800 MHz
- GPRS class 10
- Supply voltage range: 3.22 - 4.5 V DC
- DARP/SAIC support
- AT commands 3GPP 27.005, 27.007 and Telit custom AT commands and remote AT commands
- Serial port multiplexer 3GPP 27.010
- SIM Application Toolkit
- SIM Access Profile
- Python Script Interpreter embedded
- Optimized power consumption:
 - Power off < 62uA
 - Idle (registered, power saving): 1.5 mA @ DRX=9
 - Dedicated mode: 240mA @ max power level
 - GPRS cl.10: 420mA @ max power level
- 8 I/O, Analog audio, 2 A/D, 1 D/A converter, buzzer output
- Extended temperature range
 - 40°C to +85°C (Operational)
 - 40°C to +85°C (Storage temperature)
- PREMIUM FOTA MANAGEMENT

Country lock on CIS countries: RU (Russia), UA (Ukraine), BY (Belorussia), MD (Moldova), KZ (Kazakhstan) etc., Bangladesh, China, Hong Kong, India, Laos, Macao, Malaysia, Mongolia, Nepal, Pakistan, Philippine, Singapore, Sri Lanka, Taiwan, Thailand, Vietnam

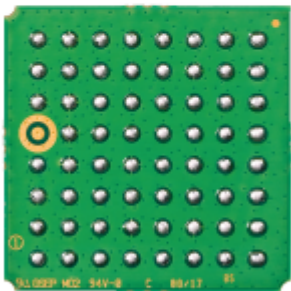


Main characteristics:

- Surface mount with metalized pads on the sides of the package
- Makes easier design of simple applications based on 4-layer PCB
- Suitable also for manual soldering (niche applications)

Comparison with BGA:

	BGA	LCC
size	22 x 22	24,4 x 24,4 (23% bigger due to the pad on the side)
I/O	More pins available (pads on the inner part)	Limited number (pads only on the sides)
Automatic soldering	Automatic pick and place standard machines	Automatic pick and place standard machines
Manual soldering	Not applicable	Yes (suitable for small, simple and low volume applications)
Thermal resistance of module/PCB junction	Low	Middle



LCC= Leadless Chip Carrier castellation mounting packaging technology

- Completed certification by end of November
- SOP on first half of October
- 2000 pcs available for the sales end of October
- Engineering P/Ns:
 - GL868-DUAL: **ENG3990250780**
 - GL865-DUAL : **ENG3990250769**
- Production P/Ns with SW 10.00.xx4 (W10/201) that can be forecasted:
 - GL868-DUAL: **GL865DUA004T001**
 - GL865-DUAL : **GL868DUA004T001**
- Product Description available (separate for 865 and 868)
- GL865-DUAL HW User Guide available
- Datasheet available